

### 1 layer FPC 35 $\mu$ m (stiffener optional)

Layer	Description	Stack-up	Thickness	Type
	Cover layer		25,4 $\mu$ m	Polyimid
	Glue		25,4 $\mu$ m	Epoxy
Top Layer 1	Copper		35,0 $\mu$ m	Cu
	Glue		25,4 $\mu$ m	Epoxy
	Base Film		25,4 $\mu$ m	Polyimid
	Glue		25,4 $\mu$ m	Epoxy
	Stiffener		200,0 $\mu$ m	Polyimid
<b>total thickness incl.</b>			<b>total thickness excl.</b>	
<b>stiffener:</b>	<b>0,362 mm</b>		<b>Stiffener:</b>	<b>0,137 mm</b>
<b>tolerance</b>	<b>10%</b>		<b>tolerance</b>	<b>10%</b>
<b>maximum thickness</b>	<b>0,398 mm</b>		<b>maximum thickness</b>	<b>0,150 mm</b>
<b>minimum thickness</b>	<b>0,326 mm</b>		<b>minimum thickness</b>	<b>0,123 mm</b>

#### NOTE:

The stack up may vary for orders in the online calculation. The upper picture is an example only.  
 The selection of the solder mask or cover lay depends on the structures in the individual mask layer.  
 For FPC orders in the online calculation LeitOn will chose between cover lay or solder mask without notification.  
 It can also happen that top and bottom layer get different treatments!